



Product Change Notification: BLAS-03KCFJ806

Date:

07-Aug-2025

Product Category:

General Purpose Fpgas

Notification Subject:

CCB 7592 Initial Notice: Qualification of HL8332NS as an additional substrate material for A3PE1500-2FG484, A3PE1500-1FG484, A3PE1500-1FG484I, A3PE1500-1FGG484, A3PE1500-1FGG484I, A3PE1500-2FG484I, A3PE1500-2FGG484, A3PE1500-2FGG484I, A3PE1500-FG484, A3PE1500-FG484I, A3PE1500-FGG484, A3PE1500-FGG484I, A3PE1500-FGG484ID, M1A3PE1500-1FG484, M1A3PE1500-1FG484I, M1A3PE1500-1FGG484, M1A3PE1500-1FGG484I, M1A3PE1500-2FG484, M1A3PE1500-2FG484I, M1A3PE1500-2FGG484, M1A3PE1500-2FGG484I, M1A3PE1500-FG484, M1A3PE1500-FG484I, M1A3PE1500-FGG484 and M1A3PE1500-FGG484I catalog part numbers (CPN) available in 484L PBGA (23x23x2.44mm) package at ATP7 assembly site.

Affected CPNs:

[BLAS-03KCFJ806_Affected_CPN_08072025.pdf](#)
[BLAS-03KCFJ806_Affected_CPN_08072025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of HL8332NS as an additional substrate material for A3PE1500-2FG484, A3PE1500-1FG484, A3PE1500-1FG484I, A3PE1500-1FGG484, A3PE1500-1FGG484I, A3PE1500-2FG484I, A3PE1500-2FGG484, A3PE1500-2FGG484I, A3PE1500-FG484, A3PE1500-FG484I, A3PE1500-FGG484, A3PE1500-FGG484I, A3PE1500-FGG484ID, M1A3PE1500-1FG484, M1A3PE1500-1FG484I, M1A3PE1500-1FGG484, M1A3PE1500-1FGG484I, M1A3PE1500-2FG484, M1A3PE1500-2FG484I, M1A3PE1500-2FGG484, M1A3PE1500-2FGG484I, M1A3PE1500-FG484, M1A3PE1500-FG484I, M1A3PE1500-FGG484 and M1A3PE1500-FGG484I catalog part numbers (CPN) available in 484L PBGA (23x23x2.44mm) package at ATP7 assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Substrate Core Material	HL832NX-A	HL832NX-A
SM Material	AUS320	AUS320
Die Attach Material	2300	2300
Solder Ball Material	SAC405	SAC405

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying HL8332NS as an additional substrate material at ATK assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: December 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: August 07, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_BLAS-03KCFJ806_Qual Plan.pdf](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [**PCN home page**](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [**PCN FAQ**](#) section.

If you wish to change your PCN profile, including opt out, please go to the [**PCN home page**](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.